ROHA

LEADER TIME SRL

PRODUCT SPECIFICATION

20*4 Characters COB LCD MODULE MODEL: LT-2004A-802 Ver:1.1

< > > Finally Specification

CUSTOMER'S APPROVAL					
CUSTOMER:					
SIG	NATURE:	DATE:			

APPROVED	PM	PD	PREPARED
BY	REVIEWD	REVIEWD	Ву

Prepared By: LEADER TIME SRL

VIA MONS. PROSDOCIMI, 27 36042 BREGANZE (VI)

• This specification is subject to change without notice. Please contact LT or its representative before designing your product based on this specification.

1/1

Revision Status

Version	Revise Date	Page	Content	Modified By
Ver 1.0	2017.08.07		First Issued	
Ver 1.1	2017.10.23	4,21	Change IC ,Modify Outline Drawing ,Add Sample No.	

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1. Features

The features of LCD are showed as follows

* Display mode : STN/Blue/Transmissive/Negative * Controller IC : UCI7066-01(English and Japanese)

* Display format :20X4 Characters

* Interface Input Data : 8 bit MPU

* Driving Method : 1/16Duty, 1/5Bias

* Viewing Direction : 60'clock

* Backlight : LED Side White

*Sample NO. : C2004A2SGW6B-B0_02/20171021

2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	98(W) x60(H) x14.0MAX(D)	mm
Viewing Area	77(W) x 26.5(H)	mm
ActivityDisplay Area	70.4(W)x20.8(H)	mm
Character Font	5x8 Dots	-
Character Size	2.95(W)x4.75(H)	mm
Character Pitch	3.55(W)x5.35(H)	mm
Dot Size	0.55(W)x0.55(H)	mm

3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Min	Max	Unit
Supply Voltage For Logic	Vdd	-0.3	+7.0	V
Supply Voltage For LCD Drive	V_{LCD}	VDD-15.0	VDD+0.3	V
Input Voltage	Vin	-0.3	VDD+0.3	V
Operating Temp.	Тор	-20	+70	°C
Storage Temp.	Tst	-30	+80	°C

^{*.} NOTE: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

3-2 ELECTRICAL CHARACTERISTICS

It	em	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Logic sup	Logic supply Voltage			4.7	5	5.3	V
LCE) Drive	$V_{\mathrm{OP}} = V_{DD} - V5$		3.9	4.2	4.5	V
	"H" Level (Except OSC1)	V _{IH1}		$0.7V_{\scriptscriptstyle DD}$	-	$V_{\scriptscriptstyle DD}$	V
	"L" Level (Except OSC1)	V _{IL1}	Ta = 25 °C VDD=5V ± 10%	-0.3	-	5.3	V
Input Voltage	"H" Level (OSC1)	V _{IH2}	0.70	$0.7 V_{DD}$	-	$V_{\scriptscriptstyle DD}$	V
	"L" Level (OSC1)	V _{IL2}		-0.2	-	$0.2V_{\scriptscriptstyle DD}$	V
Frame I	requency	f _{FLM}		-	75	75 - H	
Current C	onsumption	I _{DD}		-	2.2	-	mA

3-3BACKLIGHT

3-3-1. Absolute Maximum Ratings

Item	Symbol	Condition	min	Тур	Max	Unit
Forward Current	IF	Ta = 25 °C	-	-	75	mA
Power Dissipation	PD	Vf=4.5	-	-	270	mW
ReverseVoltage	VR	-	-	-	5	V

3-3-2. Electrical-optical Characteristics

Item	Symbol	Condition	m	in	Ту	р	Ма	ax	Unit
Forward Current	IF		-	-	45	5	60)	mA
Average Luminous Intensity	Lv	Vf=4.2V	-		24	0	-		cd/m ²
Colour coordinates	_	Ta = 25 °C	Х	Υ	Х	Υ	Х	Υ	nm
Colour coordinates			0.28	0.29	0.30	0.31	0.32	0.33	nm

The brightness is measured without LCD panel

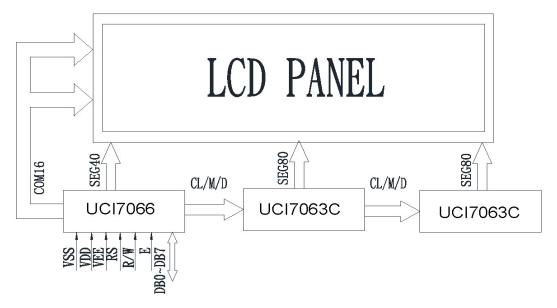
For operation above 25 °C,Thelfm&Pd must be derated, the current derating is -0.36*3mA/°C for DC drive and -0.86*3mA/°C for Pulse drive, the Power dissipation is -0.75*3mW/°C.The product working current must not more than the 60% of the lfm or lfp according to the working temperature.

4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

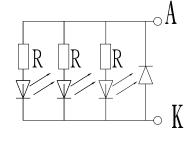
4-1INTERFACE PIN FUNCTION DESCRIPTION

PIN NO.	SYMBOL	FUNCTIONS
1	VSS	Ground
2	VDD	Supply voltage for logical circuit
3	V0	Supply voltage for LCD driving
4	RS	A signal for selecting registers. 1: Data Register (for read and write) 0: Instruction Register (for write)
5	R/W	A signal for selecting read or write actions.1: Read, 0: Write.
6	E	Aenable signal for reading or writing data.
7-14	DB0~DB7	8 Bit Data Bus
15	LEDA	Backlight(4.5V)
16	LEDK	Backlight(-)

4-2BLOCK DIAGRAM

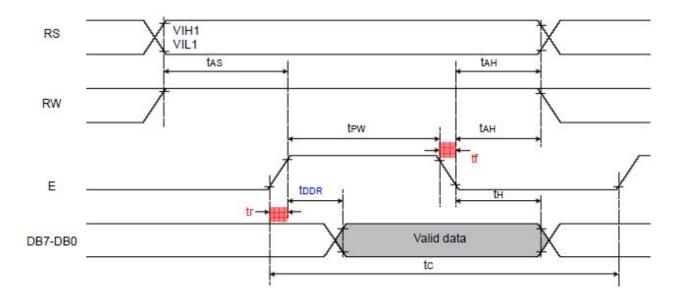




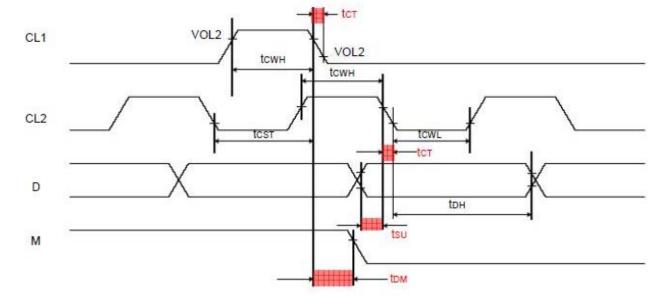


5. TIMING CHARACTERISTICS

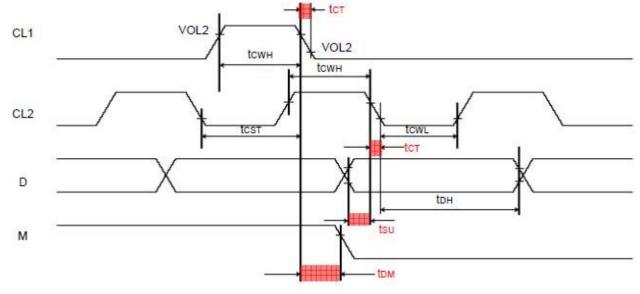
5-1 Reading data from UCI7066U to MPU



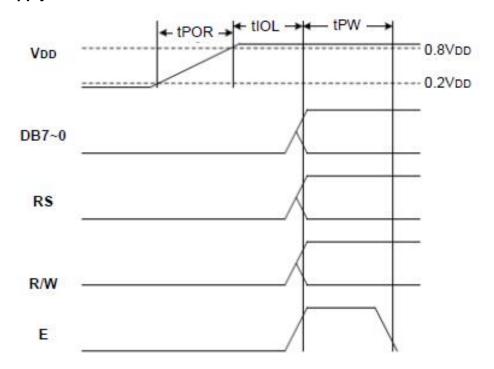
5-2 Writing data from MPU to UCI7066U



5-3 With External Driver



5-4 Power Supply Conditions



Symbol	Characteristics	Description	Min	Тур.	Max.	Unit
tPOR	Power Rise time	Power rise time that will 0.1 100 trigger internal POR circuit		100	mS	
tIOL	I/O Low time	The period that I/O is kept LOW	40			mS
tPW	Enable Pulse width	Please refer to the following tables				\$3

5-5 Parameter

TA = 25°C, Vcc=4.5V~5V

Symbol	Characteristic	Test Condition	Min.	Тур.	Max.	Unit
Internal Clock	k Operation	W:	(0)	27. Si	ži.	123
fosc	OSC Frequency	R=91ΚΩ	190	270	350	KHz
External Cloc	k Operation	78	- 10	8	/ ?	15
fex	External Frequency	-	125	270	410	KHz
	Duty Cycle	223	45	50	55	%
tr, tr	Rising/Falling Time	-	-	-	0.2	uS
Write Mode (I	MPU writes data to UCi7066)		to t			
tc	Enable Cycle Time	Pin E	1200	-	-	nS
tpw	Enable Pulse Width	Pin E	140	-	-	nS
tr, tr	Rising/Falling Time	Pin E	-	-	25	nS
tas	Address Setup Time	Pin: RS, RW, E	0	-	77	nS
tah	Address Hold Time	Pin: RS, RW, E	10	-	-	nS
tosw	Data Setup Time	Pin: DB7~DB0	40	1.7	77	nS
tн	Data Hold Time	Pin: DB7~DB0	10	1		nS
Read Mode (I	MPU reads data from UCi706	6)				
tc	Enable Cycle Time	Pin E	1200	-	-	nS
tpw	Enable Pulse Width	Pin E	140	-	77	nS
tr, tr	Rising/Falling Time	Pin E	N (22	-	25	nS
tas	Address Setup Time	Pin: RS, RW, E	0	17	7.7	nS
tah	Address Hold Time	Pin: RS, RW, E	10	-	-	nS
todr	Data Setup Time	Pin: DB7~DB0		-	100	nS
tн	Data Hold Time	Pin: DB7~DB0	10	-		nS
Interface Mod	le with LCD Driver (UCi7065))	W	20	Vi	*
tcwn	Clock Pulse Width, High	Pin: CL1, CL2	800	12		nS
tcwL	Clock Pulse Width, Low	Pin: CL1, CL2	800	-	-	nS
tcsT	Clock Setup Time	Pin: CL1, CL2	500	12	2	nS
tsu	Data Setup Time	Pin: D	300	-	-	nS
toh	Data Hold Time	Pin: D	300		2	nS
tom	M Delay Time	Pin: M	0	-	2000	nS

6.COMMAND LIST

The following is a list of host commands supported by UCi7066

R/S: 0: Control, 1: Data W/R: 0: Write Cycle, 1: Read Cycle D7-D0: -: Don't Care

#	Command	RS	R/W	D7	D6	D5	D4	D3	D2	D1	D0	Action
1	Clear Display	0	0	0	0	0	0	0	0	0	1	Clear the screen
2	Return Home	0	0	0	0	0	0	0	0	1	-	Move cursor to HOME
3	Set Entry Mode	0	0	0	0	0	0	0	1	I/D	S	I/D: Left / Right S: Shift OFF/ON
4	Display ON/OFF	0	0	0	0	0	0	1	D	С	В	D: Display OFF / ON C: Cursor OFF / ON B: Blink OFF / ON
5	Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	-	3	S/C: Screen / Cursor R/L Right / Left
6	Set Function	0	0	0	0	1	DL	N	F	-	1	DL: 4-bit / 8-bit, N: 1-line / 2-line F: 5x8 / 5x11
7	Set CGRAM address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	
8	Set DDRAM address	0	0	1	AC12	AC11	AC10	AC9	AC8	AC7	AC6	
9	Read Busy Flag and address	0	1	BF	AC19	AC18	AC17	AC16	AC15	AC14	AC13	
10	Write data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data to RAM
11	Read data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from RAM
d).	For S8/S9 Mode											
12	Status Read	1	1	0	0	0	0	0	0	0	0	Read status
12	Sidius Redu	0	1	BF	AC19	AC18	AC17	AC16	AC15	AC14	AC13	

Note:

Ensure that UCi7066 is not in the BUSY state (BF = 0) before sending an instruction from the MPU to the UCi7066. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself.

7.CHARACTER GENERATOR ROM

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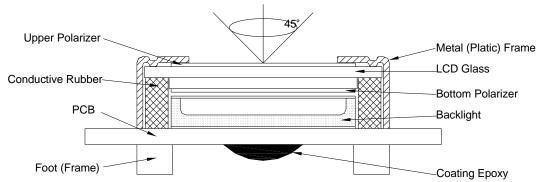
8. Polaroid

	Part no	HN1822MA					
	structure	size					
1 2 3	Release film Sticker	L=1000mm					
4 5	TAC PVA TAC	———— θ p					
6 7	Sticker Reflective Film	*release film upwards; θ p=					
	1011091170 1 11111	Polaroid absorb the shaft					

	i-	tem	unit	spec value	notes
-4	length	1	mm	1000(±10)	
size	width		mm	620(±10)	
1	effective t	hickness	μm	280±10%	
thickness	Release	film	μm	$38\pm10\%$	
Ctrin Fares	To gla	asses	gf/25mm	Above 500g	
Strip Force	Releas	se film	gf/25mm	Under 20g	
	Monomer ti	ransmittance	%	42.0±1.5	The original panel data
9	Rectangular	transmittance	%	≤2.0	The original panel data
Transmittance	380nm tr	ansmittance	%	≤1.0	
	Cutting A	ngle	٥	90 ± 1.0	
Angle	Absorption	of shaft Angle	٥	±2.0	
	BEN	DING	mm	≤±50	
	L		NBS	65.0±2.0	The original panel data
Hue		а	NBS	-1.97±2.0	The original panel data
		b	NBS	2.98±2.0	The original panel data
degree of	polarization		%	≥99.0	The original panel data
apparent d	efect (above	Diameter 150µm)		≤13/pcs	
80°C*500Hr (post- testing)Transmitt Monomer transmittance of			hange value≤	3.0%	
		Hue change ∨alue≦ No separation, no foam, str	≅ວ.∪ ipping (within	edge 0.5mm)	

9. QUALITY SPECIFICATIONS

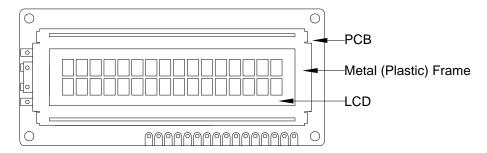
- 9-1. LCM Appearance and Electric inspection Condition
 - 1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



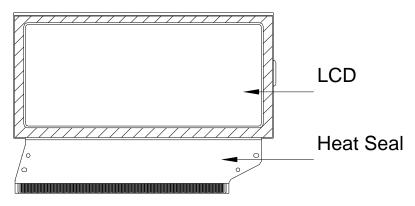
2. View Angle: with in 45° around perpendicular line.

9-2. Definition

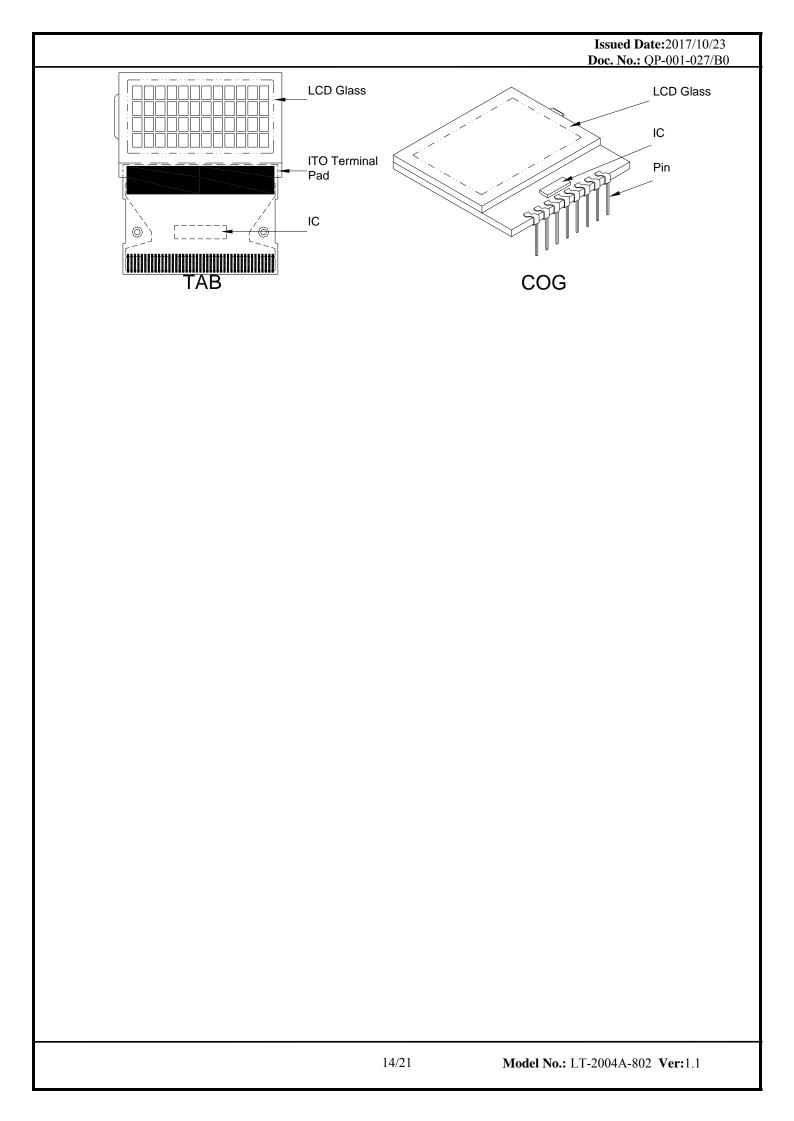
1. COB



2. Heat Seal



3. TAB and COG



9-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (||) ordinary single inspection is used.

2.Acceptance

Major defect: AQL = 0.65%Minor defect: AQL = 1.5%

9-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

2.SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing, extra, wrong component or wrong orientation		Reject
Minor	Component position shift component soldering pad x D Y	X < 3/4Z Y > 1/3D	Reject Reject
Minor	Component tilt component soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component PAD ← PCB	<i>θ</i> ≤ 20°	Reject

3. Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards					
Major	Crack / breakage	Any	Reject				
		W	L	Acceptable of Scratch			
		w<0.1mm	Any	Ignore			
		0.1 <u><</u> w<0.2mm	L <u><</u> 5.0mm	2			
Minor	Frame Scratch	0.2 <u><</u> w<0.3mm	L <u><</u> 3.0mm	1			
-		w <u>></u> 0.3mm	Any	0			
		Note: 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (not visible) can be ignored.					
				Acceptable of Dents / Pricks			
		Φ<	2				
	Frame Dent , Prick	1.0<	1				
Minor	$\Phi = \frac{L + W}{2}$	1.5	0				
	2	Note: 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (no visible) can be ignored					
Minor	Frame Deformation	Excee	d the dimension of	drawing			
Minor	Metal Frame Oxidation		Any rust				

4. Flexible F	rde						
Delect	ilish	ection Item	Inspection Standards				
Minor	Tilte	d soldering	Within the angle +5°	Acceptable			
Minor	Uneven s	older joint /bump		Reject			
			Expose the conductive line	Reject			
Minor	Hole	$\Phi = \frac{L + W}{2}$	Φ> 1.0mm	Reject			
Minor	Position shift		Y > 1/3D	Reject			
Minor	- X - - X X	- - -	X > 1/2Z	Reject			

5. Screw

Defect	Inspection Item	Inspection Standards	
Major	Screw missing/loosen		Reject
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reject

6. Heatseal . TCP . FPC

Defect	Inspection Item	Inspection Standards			
Major	Scratch expose conductive layer		Reject		
Minor	HS Hole $\Phi = \frac{L + W}{2}$	⊕> 0.5mm	Reject		
Major	Adhesion strength	Less than the specification	Reject		
Minor	Position shift	Y > 1/3D	Reject		
IVIII IOI	X X	X > 1/2Z	Reject		
Major	Conductive line break		Reject		

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards					
		Acceptable number of units					
		⊕ <u><</u> 0.10mm	Ignore				
	LED dirty, prick	0.10<⊕ <u><</u> 0.15mm	2				
Minor		0.15<⊕ <u><</u> 0.2mm	1				
		Ф>0.2mm	0				
		The distance between any two spots should be ≥ Any spot/dot/void outside of viewing area is accept					
Minor	Protective film tilt	Not fully cover LCD	Reject				
Major	COG coating	Not fully cover ITO circuit	Reject				

8. Electric Inspection

<u></u>			
Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

9. Inspection Specification of LCD

Defect	Insp	ect Item			Ins	spection	St	andards	;	
		*Glass Scratch	W		W <u><</u>	0.03	0.0	0.05/WSC	5 V	V>0.05
	Linear Defect	*Polarizer Scratch	L		L.	<5		L<3		Any
Minor		* Fiber and Linear	ACC. NO.	1			1 F		Reject	
		material	Note	L is the	e ler	ngth and W	is the	e width of	the de	fect
		* Foreign material	Φ	Φ <u><</u> 0).1	0.1<⊕ <u><</u> 0	.15).15<⊕ <u><</u> 0.	.2	Φ>0.2
	Black Spot and			3EA 100m	\ / nm²	2		1		0
Minor	Polarizer Pricked	and glass * Polarizer hole or protuberance by external force	Note	Φ is the average diameter of the defect. Distance between two defects >10mm.						
		* Unobvious	-		Φ <u><</u> (0.3	0.3<	<⊕ <u><</u> 0.5	0.	5<⊕
	White Spot	transparant foreign material between	NO.	3EA	\ / 10	00mm ²		1		0
Minor	and Bubble in polarizer	glass and glass or glass and polarizer * Air protuberance between polarizer and glass	Note		Φ is the average diameter of the defect. Distance between two defects >10mm.					
	Segment Defect			Φ <u><</u> 0.	10	0.10<⊕ <u><</u>	0.20	0.20<⊕ <u><</u> 0.25		Φ>0.25
		<u>w</u>	ACC. NO.	3EA 100m	m ²	2		1		0
Minor		W		W is m	nore	than 1/2 s	egme	ent width		Reject
			Note	$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm						
				Φ <u><</u> 0.10 0.10<		0.10<⊕≤	Ď ≤ 0.20 0.20<Φ ≤		<u><</u> 0.25	Φ>0.25
NA:	Protuberant	unt W		Glu	Glue W<1/2 S W<0.:				Ignore	
Minor	Segment	$\Phi = (L + W)/2$	ACC. NO.	3EA / 100mm²		2		1		0
			1. Seg	ment	<u> </u>					
			Е		B <u><</u>	<u>0.4mm</u>	0.4 <e< td=""><td>3<u><</u>1.0mm</td><td>B>1</td><td>.0mm</td></e<>	3 <u><</u> 1.0mm	B>1	.0mm
Miraar	Assembly		B-	Α		A<1/2B		A<0.2	B-A	<0.25
Minor	Mis-alignment			Judge Acceptable Acceptable Acceptable					eptable	
			2. Dot	Matrix						1
			Deformation>2° Reje						Reject	
Minor	Stain on LCD Panel Surface		or a	similar	one	ins can be e. Otherwi ick spot" ai	se, ju	udged acc		

10. RELIABILITY

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70°C, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity	60°C, 90%RH, 96Hrs	2	GB/T2423.3 -2006
4	High Temperature Storage	80°C, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20°C, 60min~70°C, 60min, 20 cycles.	2	GB/T2423.2 2 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	2	GB/T5170.1 4 -2009
8	Electrical Static Discharge	Air: ± 8 KV 150pF/330 Ω 5 times	2	GB/T17626.
		Contact: ± 4 KV 150pF/330 Ω 5 times		-2006
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8 -1995

Note:1) Above conditions are suitable for our company standard products.

²⁾ For restrict products, the test conditions listed as above must be revised.

11. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily getdamaged since the Module is fixed by utilizing fitting holesin the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichlorotrifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics

(3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. Andground your body, Work/assembly table. Andassembly equipment toprotect against staticelectricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.

(5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is required.

(6) Storage

In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

(7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol. Which should be burned up later.

When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

(8) Other

- After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

